

ABSTRACT

The present invention provides a laminate including an adhesive layer that has both a bonding function and a releasing function in a single layer and can be released through light irradiation, the laminate being capable of firmly bonding a support substrate to a semiconductor substrate during polishing of the semiconductor substrate and easily separating the support substrate from the semiconductor substrate through light irradiation after the polishing; an adhesive composition for forming such a releasable adhesive layer; and a method for producing a processed semiconductor substrate using the laminate. An adhesive composition for release by light irradiation for forming an adhesive layer of a laminate including a semiconductor substrate, a support substrate, and the adhesive layer provided between the semiconductor substrate and the support substrate, and the laminate being used for releasing the semiconductor substrate and the support substrate each other after the adhesive layer absorbs light emitted from a side of the support substrate, the adhesive composition including: an adhesive component (S); and a release agent component (R), wherein the adhesive component (S) contains a polysiloxane resin, and the release agent component (R) contains a (meth)acrylic polymer including a silicone-based first unit and a light-absorbing structured

second unit.

FIG. 1